AUTOMOTIVE GRADE

International

AUIRF2907ZS-7P

HEXFET[®] Power MOSFET

Features

- Advanced Process Technology
- Ultra Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified *

Description

Specifically designed for Automotive applications, this HEXFET[®] Power MOSFET utilizes the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of this design are a 175°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in Automotive applications and a wide variety of other applications.



V _{(BR)DSS}	75V
R _{DS(on)} typ.	3.0m Ω
max.	3.8m Ω®
ID (Silicon Limited)	180A



G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

Absolute Maximum Ratings

	Parameter	Max.	Units	
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)	180		
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)	120	A	
I _{DM}	Pulsed Drain Current ①	700		
P _D @T _C = 25°C	Maximum Power Dissipation	300	W	
	Linear Derating Factor	2.0	W/°C	
V _{GS}	Gate-to-Source Voltage	± 20	V	
E _{AS} Single Pulse Avalanche Energy (Thermally Limited) [©]		160	mJ	
E _{AS} (tested)	Single Pulse Avalanche Energy Tested Value (S)	410	7	
I _{AR}	Avalanche Current ①	See Fig.12a,12b,15,16	A	
E _{AR}	Repetitive Avalanche Energy ①		mJ	
TJ	Operating Junction and	-55 to + 175		
T _{STG} Storage Temperature Range			°C	
	Soldering Temperature, for 10 seconds (1.6mm from case)	300		
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)		

Thermal Resistance

	Parameter	Тур.	Max.	Units
R _{0JC}	Junction-to-Case 🗇		0.50	
R _{ecs}	Case-to-Sink, Flat, Greased Surface	0.50		°C/W
R _{0JA}	Junction-to-Ambient		62	C/VV
R _{0JA}	Junction-to-Ambient (PCB Mount, steady state) ®		40	

 $\mathsf{HEXFET}^{\texttt{®}}$ is a registered trademark of International Rectifier.

*Qualification standards can be found at http://www.irf.com/

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Static Electrical Characteristics @ $T_J = 25^{\circ}C$ (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	75			V	$V_{GS} = 0V, I_{D} = 250\mu A$
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.066		V/°C	Reference to 25°C, $I_D = 1mA$
R _{DS(on)} SMD	Static Drain-to-Source On-Resistance		3.0	3.8	mΩ	V _{GS} = 10V, I _D = 110A ③
V _{GS(th)}	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
gfs	Forward Transconductance	94			S	V _{DS} = 25V, I _D = 110A
I _{DSS}	Drain-to-Source Leakage Current			20	μA	$V_{DS} = 75V, V_{GS} = 0V$
				250		$V_{DS} = 75V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			200	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage			-200		$V_{GS} = -20V$

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
Q _g	Total Gate Charge		170	260		I _D = 110A
Q _{gs}	Gate-to-Source Charge		55		nC	$V_{DS} = 60V$
Q _{gd}	Gate-to-Drain ("Miller") Charge		66			V _{GS} = 10V ③
t _{d(on)}	Turn-On Delay Time		21			$V_{DD} = 38V$
t _r	Rise Time		90			I _D = 110A
t _{d(off)}	Turn-Off Delay Time		92		ns	$R_G = 2.6\Omega$
t _f	Fall Time		44			V _{GS} = 10V ③
L _D	Internal Drain Inductance		4.5			Between lead, 6mm (0.25in.)
Ls	Internal Source Inductance		7.5		nH	from package
C _{iss}	Input Capacitance		7580			$V_{GS} = 0V$
C _{oss}	Output Capacitance		970			$V_{DS} = 25V$
C _{rss}	Reverse Transfer Capacitance		540			f = 1.0MHz, See Fig. 5
C _{oss}	Output Capacitance		3750		pF	$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$
C _{oss}	Output Capacitance		650			$V_{GS} = 0V, V_{DS} = 60V, f = 1.0MHz$
C _{oss} eff.	Effective Output Capacitance ④		1110			$V_{GS} = 0V, V_{DS} = 0V \text{ to } 60V$

Diode Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions		
ls	Continuous Source Current		MOSFET symbol					
	(Body Diode)		160	160		showing the		
I _{SM}	Pulsed Source Current			700	700	700	A	integral reverse
	(Body Diode) ①	700		p-n junction diode.				
V_{SD}	Diode Forward Voltage			1.3	V	T _J = 25°C, I _S = 110A, V _{GS} = 0V ③		
t _{rr}	Reverse Recovery Time		35	53	ns	T _J = 25°C, I _F = 110A, V _{DD} = 38V		
Q _{rr}	Reverse Recovery Charge		40	60	nC	di/dt = 100A/µs ③		
t _{on}	Forward Turn-On Time	Intrinsic	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)					

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).
- ② Limited by T_{Jmax}, starting T_J = 25°C, L=0.026mH, R_G = 25Ω, I_{AS} = 110A, V_{GS} =10V. Part not recommended for use above this value.

③ Pulse width \leq 1.0ms; duty cycle \leq 2%.

- $@C_{oss}$ eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⁽⁵⁾ This value determined from sample failure population starting $T_J = 25^{\circ}$ C, L=0.026mH, $R_G = 25\Omega$, $I_{AS} = 110$ A, $V_{GS} = 10$ V.
- ⑥ This is applied to D²Pak, when mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- $\oslash~\mathsf{R}_{\theta}$ is measured at T_J of approximately 90°C.
- ⑧ Solder mounted on IMS substrate.

Qualification Information[†]

			Automotive		
		(per AEC-Q101) ^{††}			
Qualificati	on Level	Comments: This part number(s) passed Automotive qualificati IR's Industrial and Consumer qualification level is granted extension of the higher Automotive level.			
Moisture S	Sensitivity Level	D2 PAK 7 Pin MSL1			
	Machine Model	Class M4(425V)			
		(per AEC-Q101-002)			
500	Human Body Model	Class H2(4000V)			
ESD		(per AEC-Q101-001)			
	Charged Device Model	Class C4 (1000V)			
		(per AEC-Q101-005)			
RoHS Con	npliant	Yes			

† Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

†† Exceptions to AEC-Q101 requirements are noted in the qualification report.



Fig 1. Typical Output Characteristics



Fig 2. Typical Output Characteristics



Fig 3. Typical Transfer Characteristics



Fig 4. Typical Forward Transconductance vs. Drain Current

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Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage



Fig 7. Typical Source-Drain Diode Forward Voltage



Fig 8. Maximum Safe Operating Area



Fig 9. Maximum Drain Current vs. Case Temperature





Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



Fig 12a. Unclamped Inductive Test Circuit









Fig 12b. Unclamped Inductive Waveforms





Fig 13b. Gate Charge Test Circuit



Fig 14. Threshold Voltage vs. Temperature



Fig 15. Typical Avalanche Current vs.Pulsewidth



Fig 16. Maximum Avalanche Energy vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 15, 16: (For further info, see AN-1005 at www.irf.com)

- 1. Avalanche failures assumption:
- Purely a thermal phenomenon and failure occurs at a temperature far in excess of $T_{\text{jmax}}.$ This is validated for every part type.
- 2. Safe operation in Avalanche is allowed as long asTimax is not exceeded.
- 3. Equation below based on circuit and waveforms shown in Figures 12a, 12b.
- 4. P_{D (ave)} = Average power dissipation per single avalanche pulse.
- 5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
- 6. I_{av} = Allowable avalanche current.
- 7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 15, 16).

 $t_{av} = Average time in avalanche.$ D = Duty cycle in avalanche = $t_{av} \cdot f$

Z_{thJC}(D, t_{av}) = Transient thermal resistance, see figure 11)

$$\begin{split} P_{D~(ave)} &= 1/2~(~1.3{\cdot}BV{\cdot}I_{av}) = {{\bigtriangleup}T/~Z_{thJC}}\\ I_{av} &= 2{{\bigtriangleup}T/~[1.3{\cdot}BV{\cdot}Z_{th}]}\\ E_{AS~(AR)} &= P_{D~(ave)}{\cdot}t_{av} \end{split}$$



Fig 17. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET[®] Power MOSFETs



Fig 18a. Switching Time Test Circuit



Fig 18b. Switching Time Waveforms

6.85

D²Pak - 7 Pin Package Outline

Dimensions are shown in millimeters (inches)



D²Pak - 7 Pin Part Marking Information



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

D²Pak - 7 Pin Tape and Reel

NOTES, TAPE & REEL, LABELLING:

- 1. TAPE AND REEL.
 - 1.1 REEL SIZE 13 INCH DIAMETER.
 - 1.2 EACH REEL CONTAINING 800 DEVICES.
 - 1.3 THERE SHALL BE A MINIMUM OF 42 SEALED POCKETS CONTAINED IN THE LEADER AND A MINIMUM OF 15 SEALED POCKETS IN THE TRAILER.
 - 1.4 PEEL STRENGTH MUST CONFORM TO THE SPEC. NO. $71\!-\!9667,$
 - 1.5 PART ORIENTATION SHALL BE AS SHOWN BELOW.
 - 1.6 REEL MAY CONTAIN A MAXIMUM OF TWO UNIQUE LOT CODE/DATE CODE COMBINATIONS. REWORKED REELS MAY CONTAIN A MAXIMUM OF THREE UNIQUE LOT CODE/DATE CODE COMBINATIONS. HOWEVER, THE LOT CODES AND DATE CODES WITH THEIR RESPECTIVE QUANTITIES SHALL APPEAR ON THE BAR CODE LABEL FOR THE AFFECTED REEL.



- 2. LABELLING (REEL AND SHIPPING BAG).
 - 2.1 CUST. PART NUMBER (BAR CODE): IRFXXXXSTRL-7P
 - 2.2 CUST. PART NUMBER (TEXT CODE): IRFXXXXSTRL-7P
 - 2.3 I.R. PART NUMBER: IRFXXXXSTRL-7P
 - 2.4 QUANTITY;
 - 2.5 VENDOR CODE: IR
 - 2.6 LOT CODE:
 - 2.7 DATE CODE:



Ordering Information

Base part number	Package Type	Standard Pack	Complete Part Number	
		Form	Quantity	
AUIRF2907ZS-7P	D2Pak	Tube	50	AUIRF2907ZS-7P
		Tape and Reel Left	800	AUIRF2907ZS7PTL
		Tape and Reel Right	800	AUIRF2907ZS7PTR

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> WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 Tel: (310) 252-7105